Vishay Thin Film



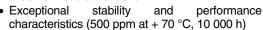
Hermetic, 50 Mil Pitch, Leadless Chip Resistor Network



Vishay Thin film offers a four terminal hermetic leadless chip carrier package with precision matched pair elements. The network features tight ratio tolerance and close tracking over a 100 Ω to 100 k Ω resistance range. For custom schematics and values contact applications engineering.

FEATURES

- Lead (Pb)-free available
- True hermetic construction





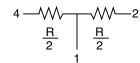
• Nickel barrier terminations

- Stable thin film resistor element (500 ppm at + 70 °C, 10 000 h)
- Military/Aerospace
- · Hermetically sealed

TYPICAL PERFORMANCE

	ABS	TRACKING
TCR	25	5
	ABS	RATIO
TOL	0.1	0.05

SCHEMATIC



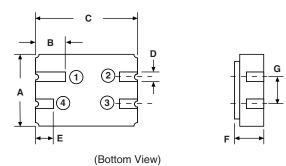
STANDARD ELECTRICAL SPECIFICATIONS			
TEST		SPECIFICATIONS	CONDITIONS
Material		Passivated nichrome	
Resistance Range	e	100 Ω to 100 kΩ	
TCR:	Tracking	± 2 ppm/°C (typical < 1 ppm/°C equal values)	- 55 °C to + 125 °C
	Absolute	± 25 ppm/°C standard	- 55 °C to + 125 °C
Tolerance:	Ratio	± 0.1 % to ± 0.05 %	+ 25 °C
	Absolute	± 1.0 % to ± 0.1 %	+ 25 °C
Power Rating:	Resistor	1000 mW per element	Max. at + 70 °C
	Package	250 mW	Max. at + 70 °C
Stability:	∆R Absolute	0.10 %	2000 h at + 70 °C
	∆ <i>R</i> Ratio	0.03 %	2000 h at + 70 °C
Voltage Coefficie	nt	< 0.1 ppm/V	
Working Voltage		50 V	
Operating Tempe	rature Range	- 55 °C to + 125 °C	
Storage Tempera	ture Range	- 55 °C to + 125 °C	
Noise		< - 30 dB	
Thermal EMF		0.08 μV/°C	
Absolute		< 100 ppm	1 year at + 25 °C
Shelf Life Stability:	y: ————————————————————————————————————	< 20 ppm	1 year at + 25 °C

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply



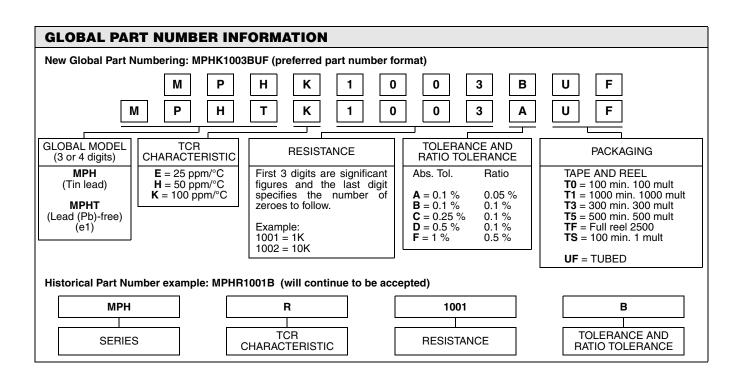
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DIMENSIONS in inches and millimeters



DIMENSIONS	INCHES	мм
А	0.155	3.937
В	0.080	2.032
С	0.225	5.715
D	0.025 typical	0.635
E	0.040	1.016
F	0.070	1.778
G	0.050	1.27

MECHANICAL SPECIFICATIONS		
Resistive Element	Passivated nichrome	
Substrate Material	Alumina	
Body	Ceramic	
Terminals	Gold over nickel	
Marking Resistance to Solvents	Per MIL-PRF-83401	
Lead (Pb)-free Option	96.5 % Sn, 3.0 % Ag, 0.5 % Cu	
Lead (Pb)-free Finish	Hot solder dip	





Vishay

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